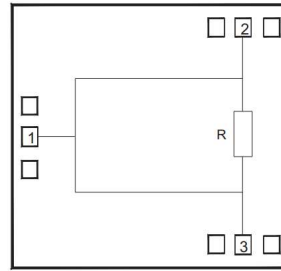


### Performance

- Frequency: 3~9GHz
- Insertion loss: 0.6dB
- Chip size: 1.27\*1.01\*0.1mm

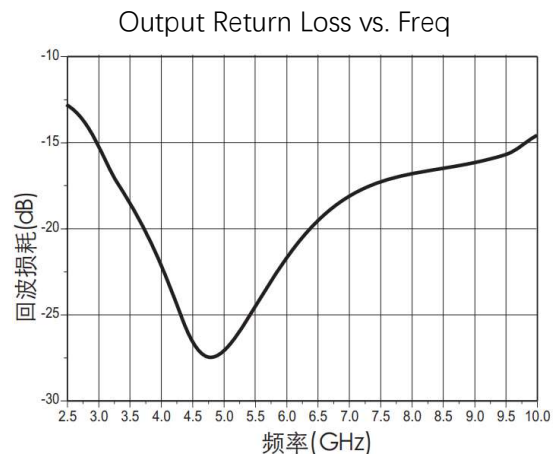
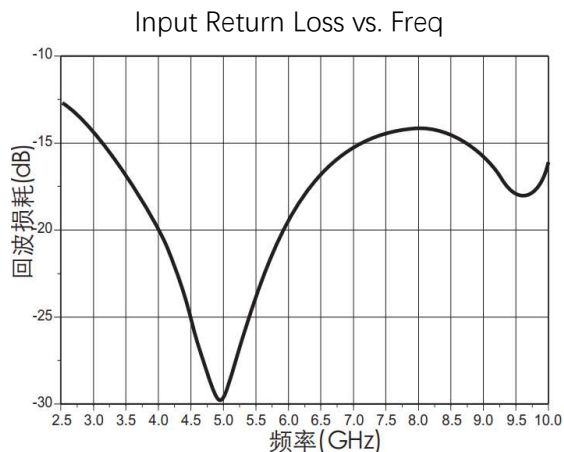
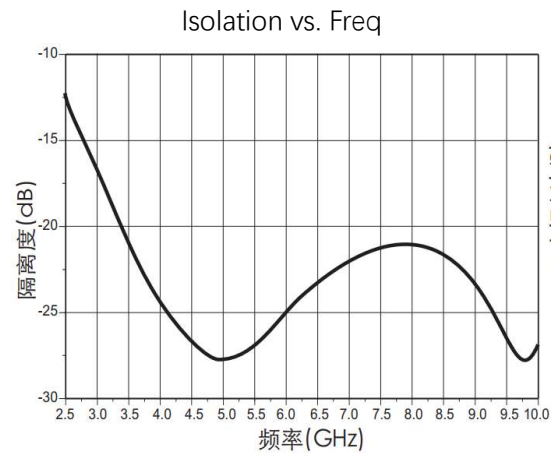
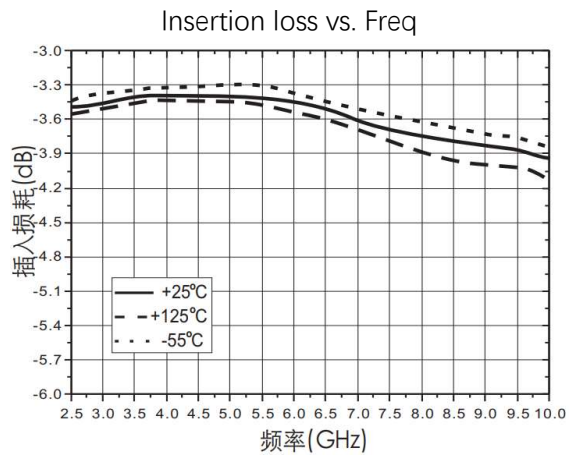
### Function Diagram



### Electrical Specifications (Ta=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range	3~9			GHz
Insertion Loss	-	0.6	1.0	dB
Insertion Loss Ripple	-	±0.3	-	dB
Isolation	15	20	-	dB
Input Return Loss	13	15	-	dB
Output Return Loss	15	18	-	dB

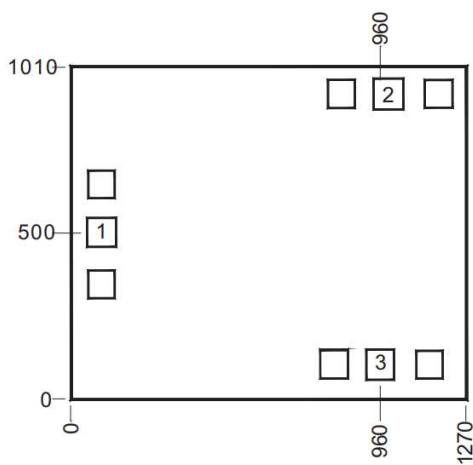
### Test Curves



### Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1A

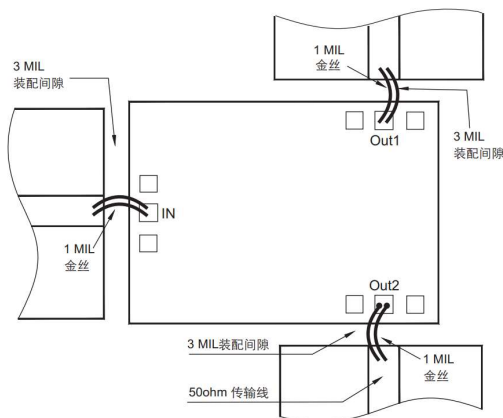
### Outline Size



### Note:

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size:  $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance:  $\pm 50 \mu\text{m}$

### Assembly Diagram



### Bonding Definition

No.	Symbol	Description
1	IN	RF input, 50ohm
2,3	Out1, Out2	RF output, 50ohm
	GND	Bottom must be grounded